JUN 2 0 2005

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

n re application of: Bolken et al.

Application No. 10/731,995 Filed: December 9, 2003 Confirmation No. 5870

PACKAGES FOR SEMICONDUCTOR

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Examiner: Scott B. Geyer

Art Unit: 2812

Attorney Reference No. 6047-67518-01

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I hereby certify that this paper and the documents referred to as being attached or enclosed herewith are being deposited with the United States Postal Service as First Class Mail in an envelope addressed to: MAIL STOP AF, COMMISSIONER FOR PATENTS, P.O. BOX 1450, ALEXANDRIA, VA 22313-1450 on the date shown below.

Attorney or Agent for Applicant(s)

Date Mailed June 17, 2005

AMENDMENT

This responds to the Office action dated April 18, 2005. Please amend the referenced application as follows:

Amendments to the Specification begin on page 2.

Amendments to the Claims are reflected in the listing of claims, which begins on page 3.

Amendments to the Drawings begin on page 6, and include the attached replacement sheets.

Remarks begin on page 7.